

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings†

Drain-to-Source Voltage	BV_{DSS}
Drain-to-Gate Voltage	BV_{DGS}
Gate-to-Source Voltage	$\pm 20V$
Operating Ambient Temperature, T_A	$-55^{\circ}C$ to $+150^{\circ}C$
Storage Temperature, T_S	$-55^{\circ}C$ to $+150^{\circ}C$

† **Notice:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

Electrical Specifications: $T_A = 25^{\circ}C$ unless otherwise specified. All DC parameters are 100% tested at $25^{\circ}C$ unless otherwise stated. (Pulse test: 300 μs pulse, 2% duty cycle)

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
Drain-to-Source Breakdown Voltage	BV_{DSS}	200	—	—	V	$V_{GS} = 0V, I_D = 2\text{ mA}$
Gate Threshold Voltage	$V_{GS(th)}$	0.6	—	1.6	V	$V_{GS} = V_{DS}, I_D = 1\text{ mA}$
Change in $V_{GS(th)}$ with Temperature	$\Delta V_{GS(th)}$	—	—	-5	mV/ $^{\circ}C$	$V_{GS} = V_{DS}, I_D = 1\text{ mA}$ (Note 1)
Gate Body Leakage Current	I_{GSS}	—	—	100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
Zero-Gate Voltage Drain Current	I_{DSS}	—	—	10	μA	$V_{GS} = 0V,$ $V_{DS} = \text{Maximum rating}$
		—	—	1	mA	$V_{DS} = 0.8 \text{ Maximum rating},$ $V_{GS} = 0V, T_A = 125^{\circ}C$ (Note 1)
On-State Drain Current	$I_{D(ON)}$	0.5	—	—	A	$V_{GS} = 5V, V_{DS} = 25V$
		1	—	—	A	$V_{GS} = 10V, V_{DS} = 25V$
Static Drain-to-Source On-State Resistance	$R_{DS(ON)}$	—	6	8	Ω	$V_{GS} = 5V, I_D = 250\text{ mA}$
		—	4	6	Ω	$V_{GS} = 10V, I_D = 500\text{ mA}$
Change in $R_{DS(ON)}$ with Temperature	$\Delta R_{DS(ON)}$	—	—	1.4	%/ $^{\circ}C$	$V_{GS} = 10V, I_D = 500\text{ mA}$ (Note 1)

Note 1: Specification is obtained by characterization and is not 100% tested.

AC ELECTRICAL CHARACTERISTICS

Electrical Specifications: $T_A = 25^\circ\text{C}$ unless otherwise specified. All AC parameters are sample tested. Specification is obtained by characterization and is not 100% tested.

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
Forward Transconductance	G _{FS}	300	400	—	mmho	V _{DS} = 25V, I _D = 500 mA
Input Capacitance	C _{ISS}	—	110	150	pF	V _{GS} = 0V, V _{DS} = 25V, f = 1 MHz
Common-Source Output Capacitance	C _{OSS}	—	40	85	pF	
Reverse Transfer Capacitance	C _{RSS}	—	10	35	pF	
Turn-On Delay Time	t _{d(ON)}	—	—	10	ns	V _{DD} = 25V, I _D = 1A, R _{GEN} = 25Ω
Rise Time	t _r	—	—	8	ns	
Turn-Off Delay Time	t _{d(OFF)}	—	—	20	ns	
Fall Time	t _f	—	—	20	ns	
DIODE PARAMETER						
Diode Forward Voltage Drop	V _{SD}	—	—	1.8	V	V _{GS} = 0V, I _{SD} = 1A (Note 1)
Reverse Recovery Time	t _{rr}	—	300	—	ns	V _{GS} = 0V, I _{SD} = 1A

Note 1: All DC parameters are 100% tested at 25°C unless otherwise stated.
(Pulse test: 300 μs pulse, 2% duty cycle)

TEMPERATURE SPECIFICATIONS

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
TEMPERATURE RANGE						
Operating Ambient Temperature	T_A	-55	—	+150	$^\circ\text{C}$	
Storage Temperature	T_S	-55	—	+150	$^\circ\text{C}$	
PACKAGE THERMAL RESISTANCE						
3-lead TO-92	θ_{JA}	—	132	—	$^\circ\text{C/W}$	

THERMAL CHARACTERISTICS

Package	I_D (Note 1) (Continuous) (mA)	I_D (Pulsed) (A)	Power Dissipation at $T_A = 25^\circ\text{C}$ (W)	I_{DR} (Note 1) (mA)	I_{DRM} (A)
3-lead TO-92	250	2	1	250	2

Note 1: I_D (continuous) is limited by maximum rated T_J .

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g. outside specified power supply range) and therefore outside the warranted range.

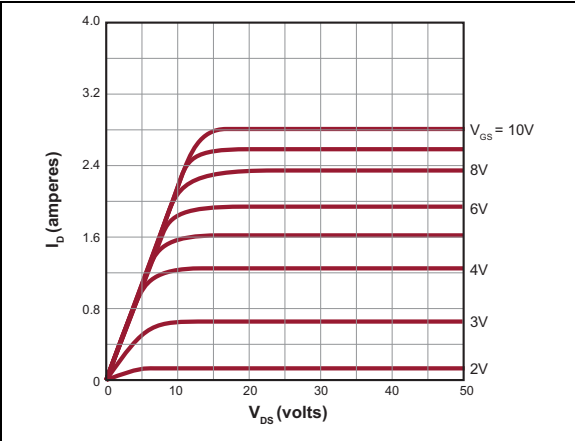


FIGURE 2-1: Output Characteristics.

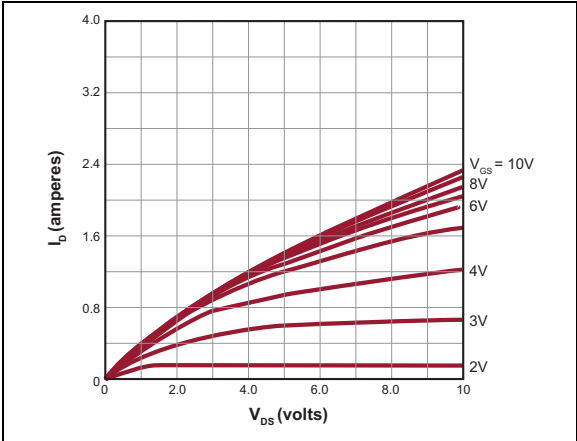


FIGURE 2-4: Saturation Characteristics.

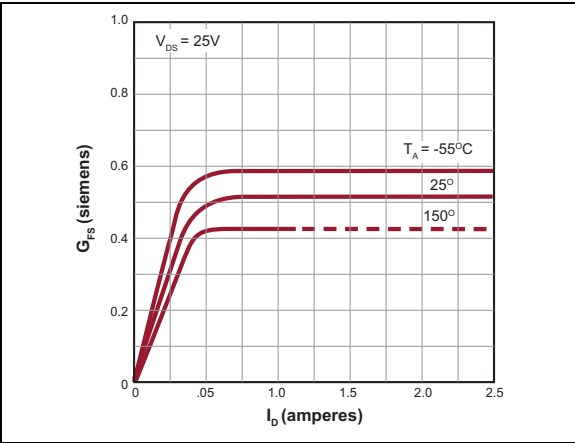


FIGURE 2-2: Transconductance vs. Drain Current.

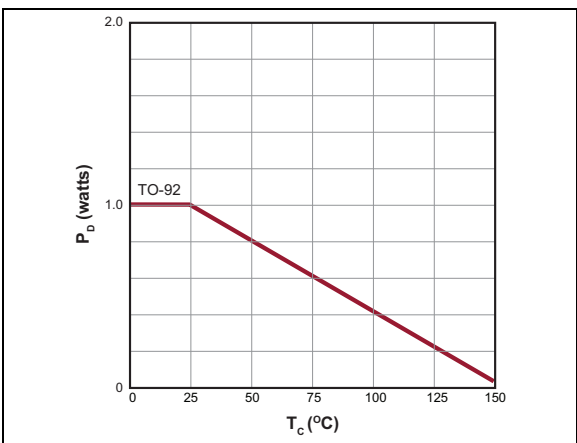


FIGURE 2-5: Power Dissipation vs. Case Temperature.

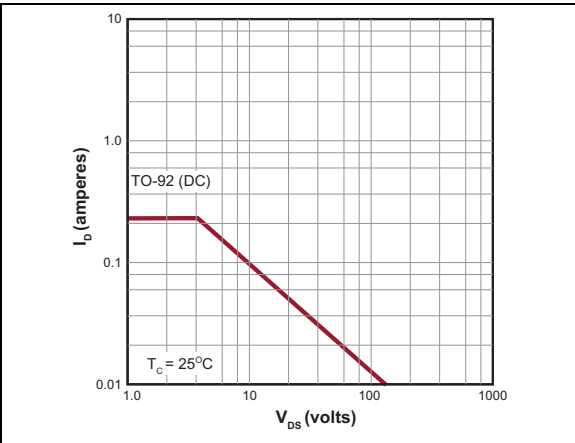


FIGURE 2-3: Maximum Rated Safe Operating Area.

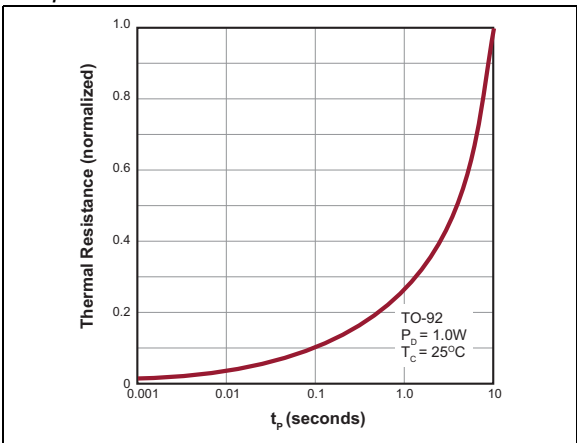


FIGURE 2-6: Thermal Response Characteristics.

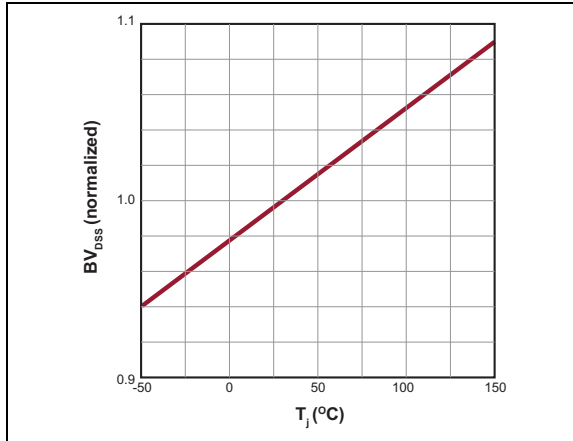


FIGURE 2-7: BV_{DSS} Variation with Temperature.

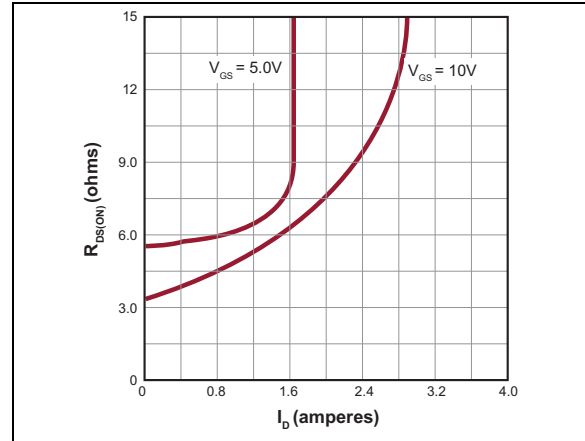


FIGURE 2-10: On-Resistance vs. Drain Current.

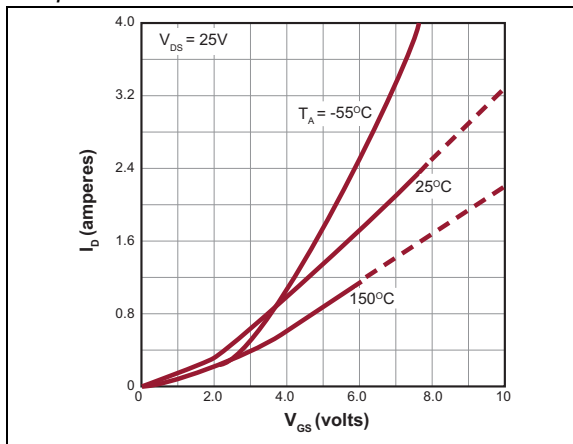


FIGURE 2-8: Transfer Characteristics.

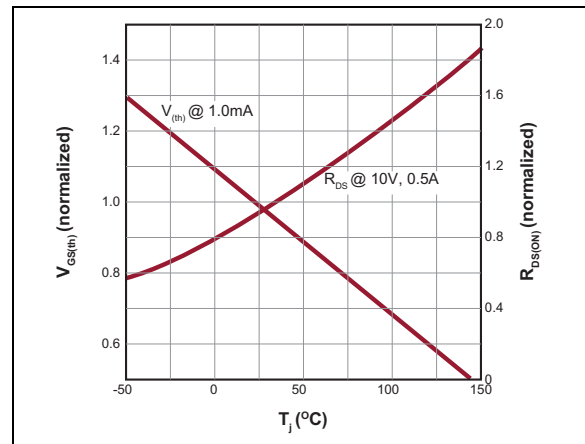


FIGURE 2-11: $V_{(th)}$ and R_{DS} Variation with Temperature.

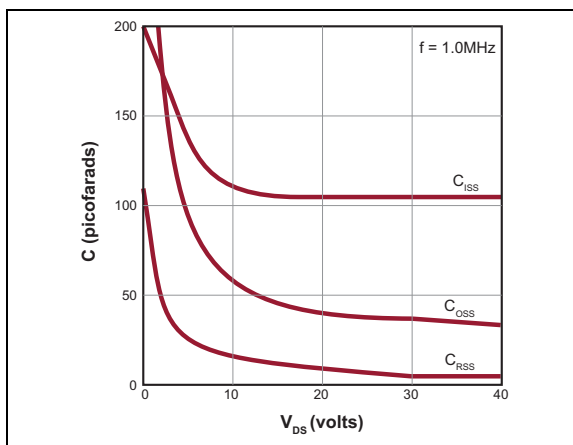


FIGURE 2-9: Capacitance vs. Drain-to-Source Voltage.

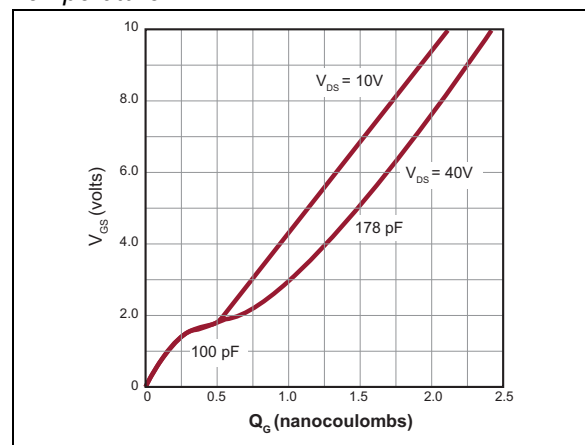


FIGURE 2-12: Gate Drive Dynamic Characteristics.

3.0 PIN DESCRIPTION

Table 3-1 shows the description of pins in TN0620.
Refer to [Package Type](#) for the location of pins.

TABLE 3-1: PIN FUNCTION TABLE

Pin Number	Pin Name	Description
1	Source	Source
2	Gate	Gate
3	Drain	Drain

4.0 FUNCTIONAL DESCRIPTION

Figure 4-1 illustrates the switching waveforms and test circuit for TN0620.

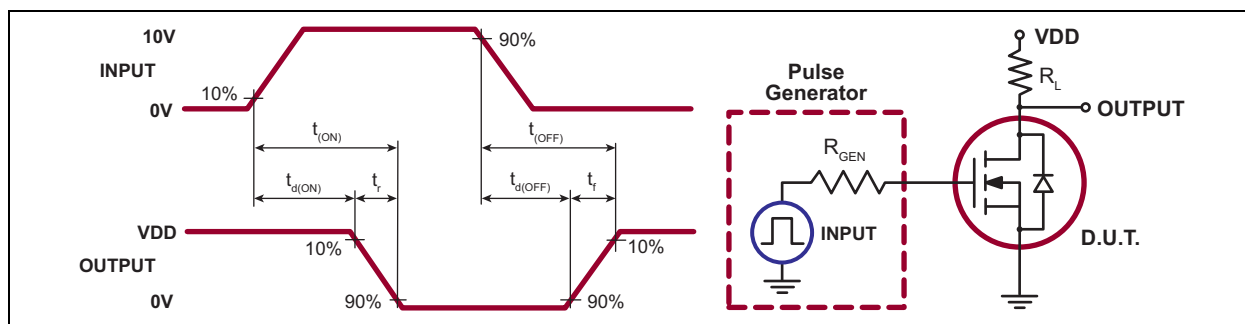


FIGURE 4-1: Switching Waveforms and Test Circuit.

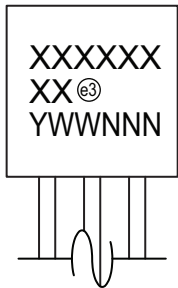
TABLE 4-1: PRODUCT SUMMARY

BV_{DSS}/BV_{DGS} (V)	$R_{DS(ON)}$ (Maximum) (Ω)	$I_{D(ON)}$ (Minimum) (A)	$V_{GS(th)}$ (Maximum) (V)
200	6	1	1.6

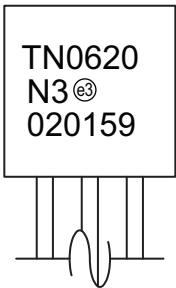
5.0 PACKAGING INFORMATION

5.1 Package Marking Information

3-lead TO-92

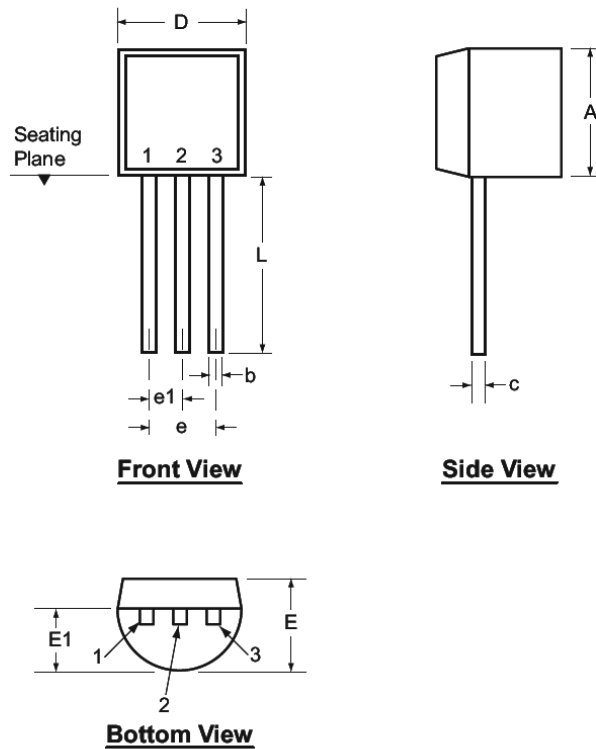


Example



Legend:	XX...X	Product Code or Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC [®] designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.
Note:	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for product code or customer-specific information. Package may or not include the corporate logo.	

3-Lead TO-92 Package Outline (L/LL/N3)



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

Symbol		A	b	c	D	E	E1	e	e1	L
Dimensions (inches)	MIN	.170	.014 [†]	.014 [†]	.175	.125	.080	.095	.045	.500
	NOM	-	-	-	-	-	-	-	-	-
	MAX	.210	.022 [†]	.022 [†]	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.

* This dimension is not specified in the JEDEC drawing.

† This dimension differs from the JEDEC drawing.

Drawings not to scale.

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (July 2020)

- Converted Supertex Doc# DSFP-TN0620 to Microchip DS20005936A
- Changed the package marking format
- Updated the packing medium of TN0620 TO-92 N3 P002 media type from 2000/Reel to 2000/Reel (Reverse T/R) to align it with the actual BQM
- Updated the packing medium of TN0620 TO-92 N3 P014 media type from 2000/Reel to 2000/Reel (Ammo Pack) to align it with the actual BQM
- Removed the TN0620 TO-92 N3 P003, P005, and P013 media types
- Made minor text changes throughout the document

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

<u>PART NO.</u>			<u>XX</u>	-	<u>X</u>	-	<u>X</u>
Device			Package Options		Environmental		Media Type
Device:	TN0620	=	N-Channel Enhancement-Mode Vertical DMOS FET				
Package:	N3	=	3-lead TO-92				
Environmental:	G	=	Lead (Pb)-free/RoHS-compliant Package				
Media Types:	(blank)	=	1000/Bag for an N3 Package				
	P002	=	2000/Reel (Reverse T/R) for an N3 Package				
	P014	=	2000/Reel (Ammo Pack) for an N3 Package				

Examples:

a) TN0620N3-G: N-Channel Enhancement-Mode, Vertical DMOS FET, 3-lead TO-92, 1000/Bag

b) TN0620N3-G-P002: N-Channel Enhancement-Mode, Vertical DMOS FET, 3-lead TO-92, 2000/Reel (Reverse T/R)

c) TN0620N3-G-P014: N-Channel Enhancement-Mode, Vertical DMOS FET, 3-lead TO-92, 2000/Reel (Ammo Pack)

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